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REMARKS

The Examiner's Action of April 7, 2005 has been received and its contents carefully considered. Reconsideration is respectfully requested in view of the following comments.

Claims 10-19 are currently pending in the instant application.

I Amendments

Claims 10 and 14 have been amended, and new claims 18 and 19 have been added. Support for the amendments may be found among others in the specification at paragraph [0003]. It is noted that new claims 18 and 19 are patentable over the applied prior art at least for the same reasons as those advanced with respect to claim 10-15 below.

II. Rejection under 35 USC 102(e)

Claims 10-15 have been rejected as being anticipated by Yoda et al. Reconsideration is respectfully requested in view of the following comments.

Yoda et al. fail to disclose a space transformer as recited in independent claims 10 and 14 where the land grid array side contacts are configured to be connected to corresponding contacts of a test card printed circuit board of a test card assembly. In addition, Yoda et al. fail to disclose a space transformer as recited in independent claims 10 and 14 where the semiconductor side contacts are configured to be connected to

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corresponding contacts of a probe head of the test card assembly. Yoda et al. pertain to an interposer. The noted features are simply missing from Yoda et al.

In view of the above, it is respectfully requested that the Examiner reconsider and withdraw his rejection of the claims under Section 102(c) as being anticipated by Yoda et al.

III. Rejection under 35 USC 103(a)

A. **Van Pham et al. in view of Eldridge et al.**

Claims 10 12 and 14 have been rejected under 35 USC 103(a) as being unpatentable over Van Pham et al. (Van Pham) in view of Eldridge et al. (Eldridge). Reconsideration is respectfully requested.

Van Pham fails to disclose a space transformer as recited in independent claims 10 and 14 where the land grid array side contacts are configured to be connected to corresponding contacts of a test card printed circuit board of a test card assembly. In addition, Van Pham fail to disclose a space transformer as recited in independent claims 10 and 14 where the semiconductor side contacts are configured to be connected to corresponding contacts of a probe head of the test card assembly.

In addition, the interposer in Van Pham does not possess electrical contact zones being disposed to convert a macro-pitch scale of the land grid array side contacts to the micro-pitch scale of the semiconductor side contacts as recited in independent claims 10 and 14. As seen in Van Pham's Figs. 3A, 3B and 4, the contacts 18 on the die side (arguably corresponding semiconductor side contacts) have spacings as follows: (a) at

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the periphery of interposer body 12, the contacts 18 have spacings that are smaller than spacings between contacts 20 on the substrate side of interposer body 12 (see Figs. 3A and 3B); AND (b) from one side of interposer body 12 to another side of interposer body 12, the contacts 18 have spacings that are appreciably larger than spacings between contacts 20 on the substrate side of interposer body 12 (see Fig. 4). The above having been said, as further seen in Fig. 4, conduits 22 in Van Pham convert the scale defined by the spacings between contacts 20 into the appreciably large scale defined by the spacings between contacts 18, the relative spacings having been described in (b) above. Thus, any scale conversion in Van Pham is exactly opposite to that according to embodiments of the present invention as recited in independent claims 10 and 14.

The long and the short of it with respect to Van Pham et al. is that (1) they do not disclose a space transformer; (2) that, although there is disclosed in Van Pham et al. a structure that is adapted to be positioned between a semiconductor and another element (in Van Pham et al.'s case, a substrate), that fact alone does not justify the leap into the argument that, as a result, that structure can be a space transformer; and (3) that, in any event, even if one were, for argument's sake, to make the leap in (2) above, one would at best arrive at a structure having electrical contact zones that convert a smaller scale as defined by smaller contact spacings into a larger scale as defined by larger contact spacings on the die side of the structure. As a result, Van Pham et al. in fact teach away from Examiner's combination of the references.

As also noted previously, Eldridge does nothing to overcome the deficiencies in Van Pham. There is no suggestion in either Van Pham or in Eldridge to combine the

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references as suggested by the Examiner to arrive at embodiments of the instant invention as recited in independent claims 10 and 14.

In view of the above, it is respectfully requested that the Examiner reconsider and withdraw his rejection of the claims under Section 103(a) as being unpatentable over Van Pham et al. in view of Eldridge et al.

B. Van Pham in view of Eldridge, further in view of Petrarca et al., and Matsuo et al.

Claims 13 and 15 have been rejected under Section 103(a) as being unpatentable over a combination of Van Pham in view of Eldridge, further in view of Petrarca et al. (Petrarca) and Matsuo et al (Matsuo). Reconsideration is respectfully submitted in view of the following comments.

Petrarca and Matsuo have been cited for their disclosure of an adhesion promoter. These references, however, fail to make up for the deficiencies of Van Pham and of Eldridge noted above.

In view of the above, it is respectfully requested that the Examiner reconsider and withdraw his rejection of the claims under Section 103(a) as being unpatentable over Van Pham in view of Eldridge, and further in view of Petrarca and Matsuo.

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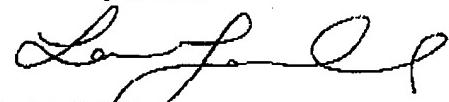
CONCLUSION

All of the stated grounds of rejection have been properly traversed, accommodated, or rendered moot. Applicant therefore respectfully requests that the Examiner reconsider all currently outstanding rejections and that they be withdrawn. It is believed that a full and complete response has been made to the outstanding Office Action and, as such, the present application is in condition for allowance. If the Examiner believes, for any reason, that personal communication will expedite prosecution of this application, the Examiner is invited to telephone the undersigned at the number provided.

Prompt and favorable consideration of this Response is respectfully requested.

Respectfully submitted,

Intel Corporation



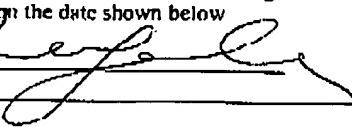
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By: 
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Date: August 8, 2005